

Message from the High Performance Computing and Communications 2022 General Chairs

Welcome to the 24th IEEE International Conference on High Performance Computing and Communications (HPCC 2022) held in Chengdu, China, on December 18-21, 2022. On behalf of the Organizing Committee of HPCC 2022, we would like to express our sincere and warm welcome to all of participants!

IEEE HPCC 2022 conference is the 24th edition of the highly successful International Conference on HPCC. It provides a forum for engineers and scientists in academia, industry, and government to address the resulting profound challenges and to present and discuss their new ideas, research results, applications and experience on all aspects of HPCC. For the IEEE HPCC 2022, the financial sponsors are IEEE and IEEE Computer Society, the technical sponsors are IEEE Technical Committee on Scalable Computing, Task Force on Cyber-Physical-Social Systems of IEEE Smart World Technical Committee. The organizers of IEEE HPCC 2022 are Sichuan University and Hainan University.

For the successful initialization and organization of this international conference with this size and diversity, we counted on the great support of many people and organizations. First of all, we would like to sincerely thank Laurence T. Yang (Hainan University, China) and Beniamino Di Martino (Second University of Naples, Italy), the Steering Chairs of HPCC, for giving us the opportunity to organize the conference and for their support and guidance. Special thanks to all steering committee members for their kind supports.

We would like to express our special thanks to the Program Chairs Yunquan Zhang (Chinese Academy of Sciences, China), Jidong Zhai (Tsinghua University, China), and Rajiv Ranjan (Newcastle University, UK) for their excellent work and great efforts in organizing an outstanding program committee, conducting a rigorous review process and selecting high quality papers from a large number of submissions, and for preparing an excellent conference program. We are grateful to the Special Session Chairs Md Arafatur Rahman (University Malaysia Pahang, Malaysia), and Laizhong Cui (Shenzhen University, China), as well as other chairs for their great supports. We would like to thank all TPC members for their hard review tasks, for providing constructive feedback to authors and enabling an excellent selection of the papers. Most importantly, our great appreciation to all authors, for submitting their high-quality papers to HPCC 2022. Last but not least, we would like to extend our thanks the HPCC 2022 organization team for the excellent arrangement of the conference.

We thank all of you for participating in HPCC 2022, and hope you find the conference stimulating and interesting for your research and professional activities. We hope IEEE HPCC can become one of the best conferences in its field.

Jack Dongarra, University of Tennessee, USA

Kenli Li, Hunan University, China

Hai Jin, Huazhong University of Science and Technology, China

General Chairs of HPCC 2022